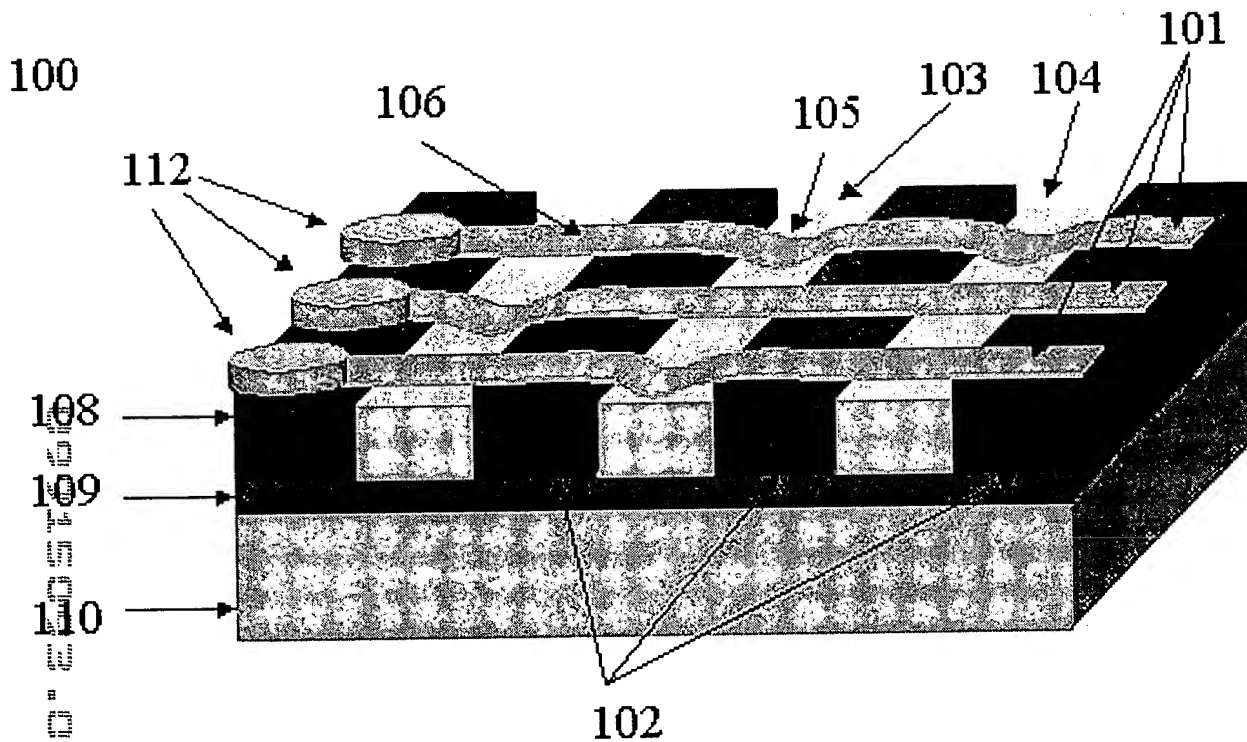


Figure 1



EXPRESS MAIL LABEL NO. 96538 701593 US
 DATE OF DEPOSIT 7-25-01

Figure 2

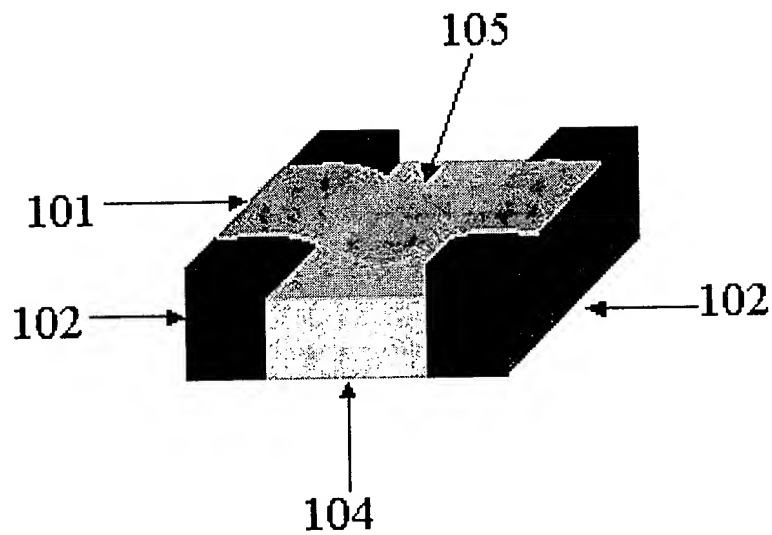
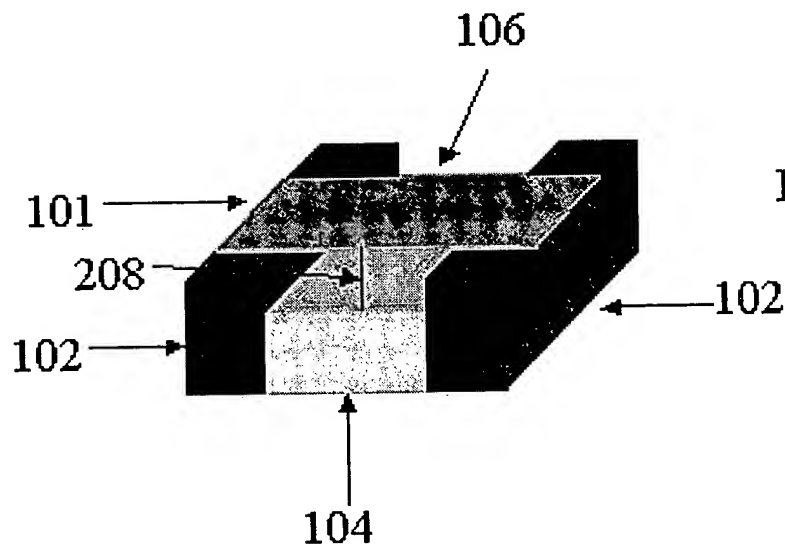


FIG. 2A

Figure 3

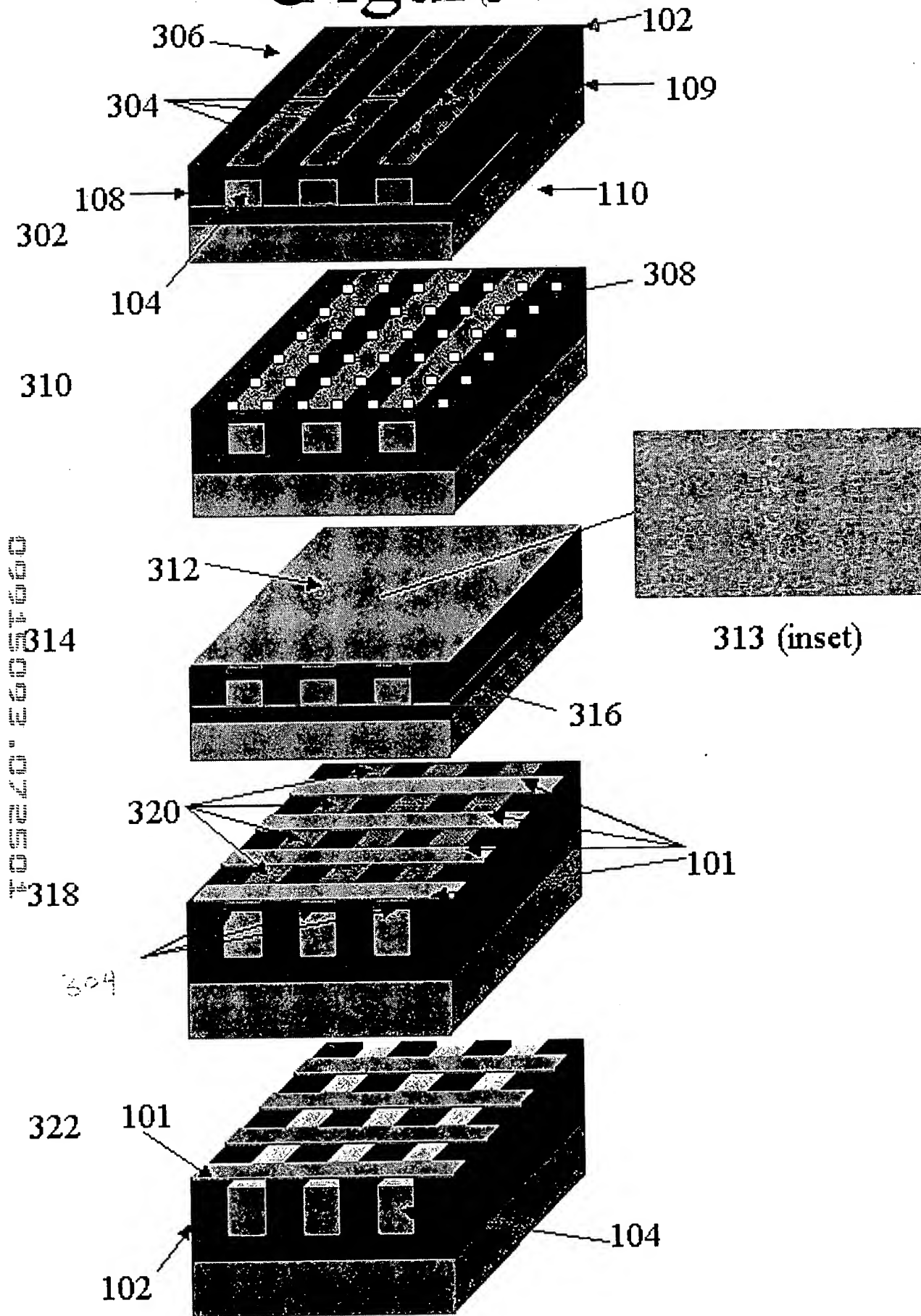


Figure 4

FIG. 4 is a cross-sectional view of a semiconductor device in accordance with one embodiment of the present invention.

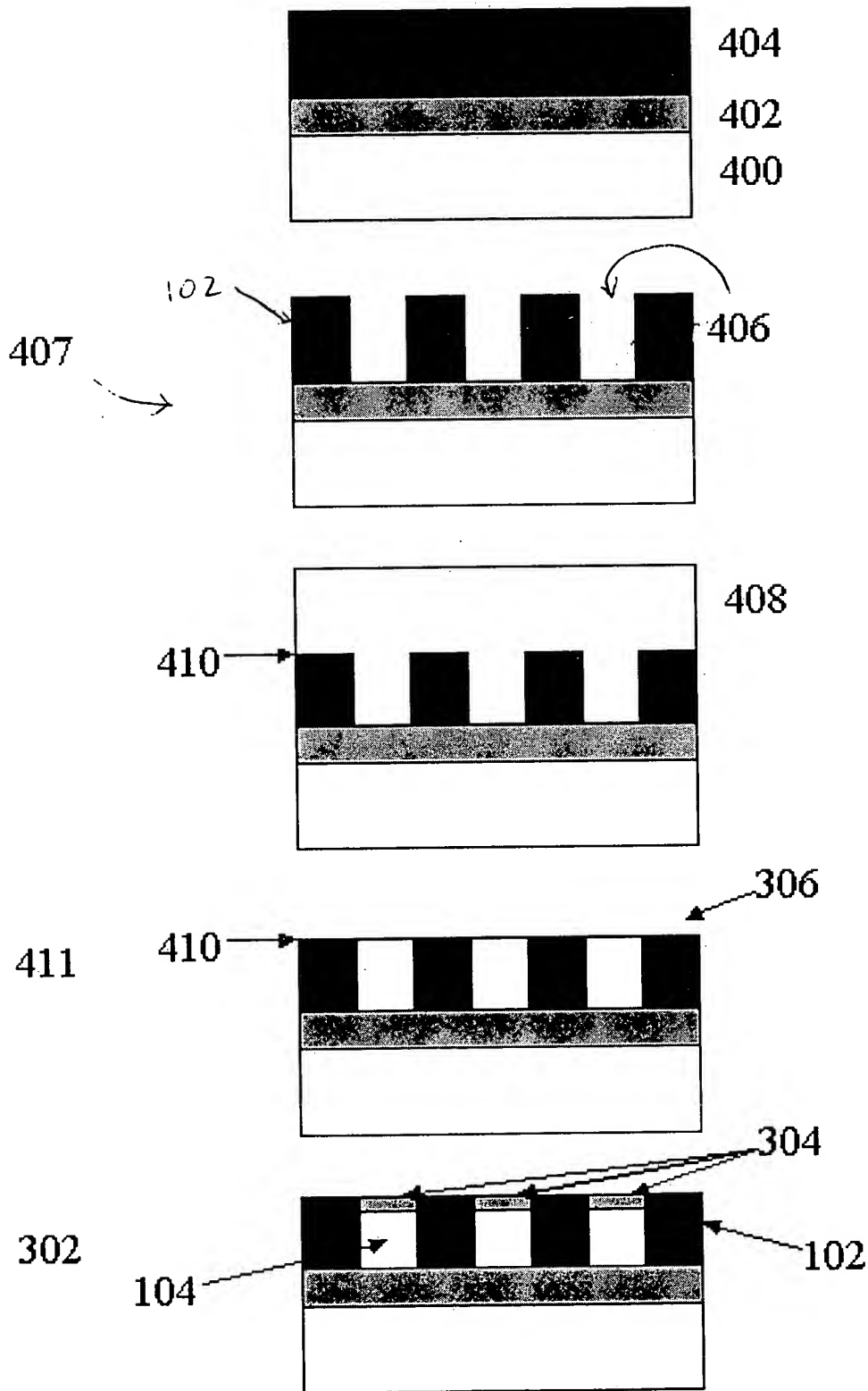


Figure 5

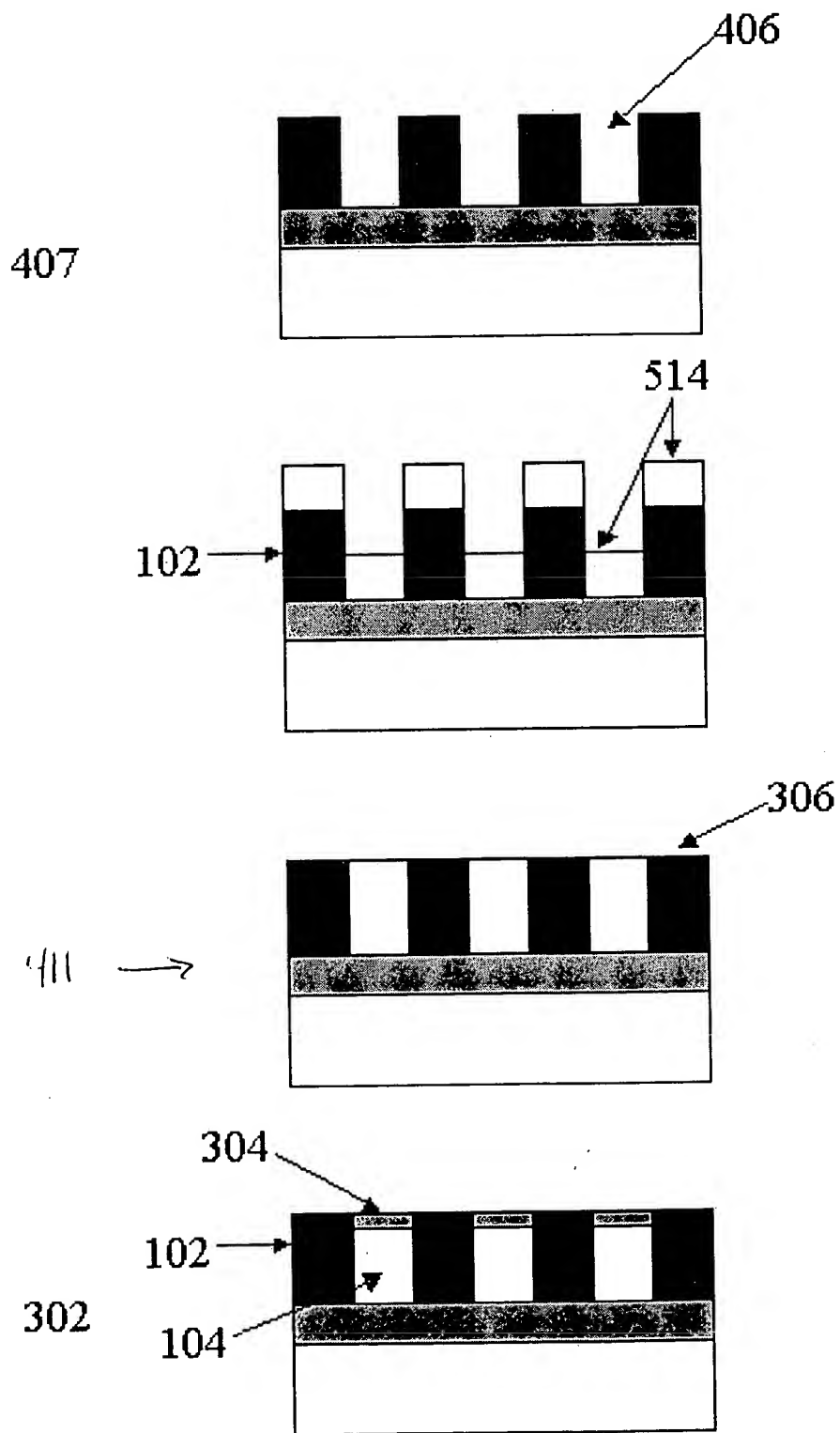


Figure 6

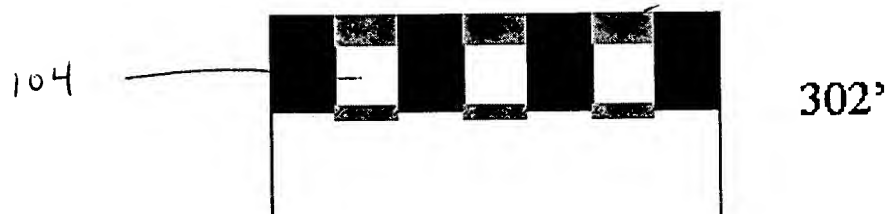
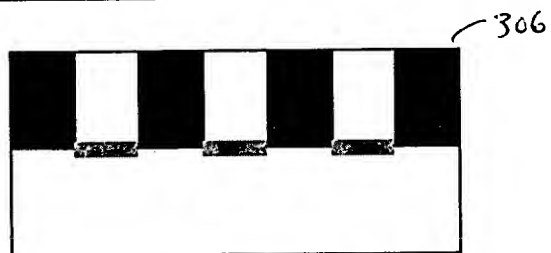
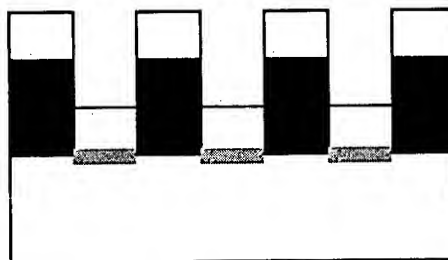
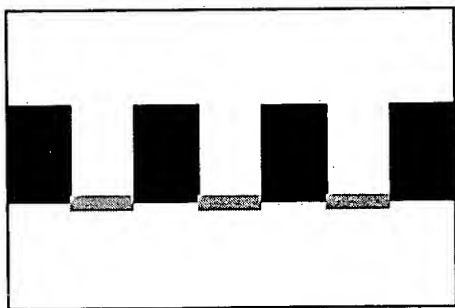
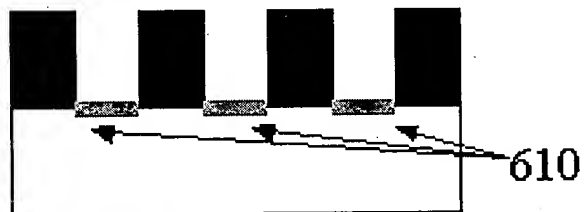
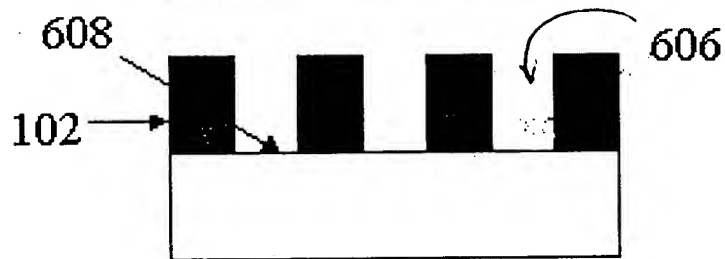
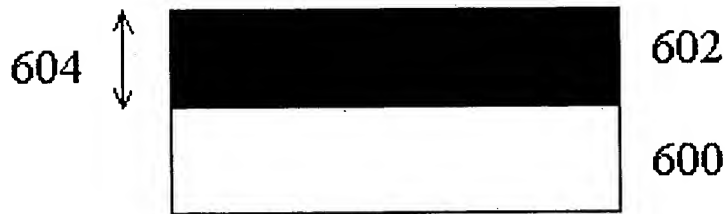


Figure 7

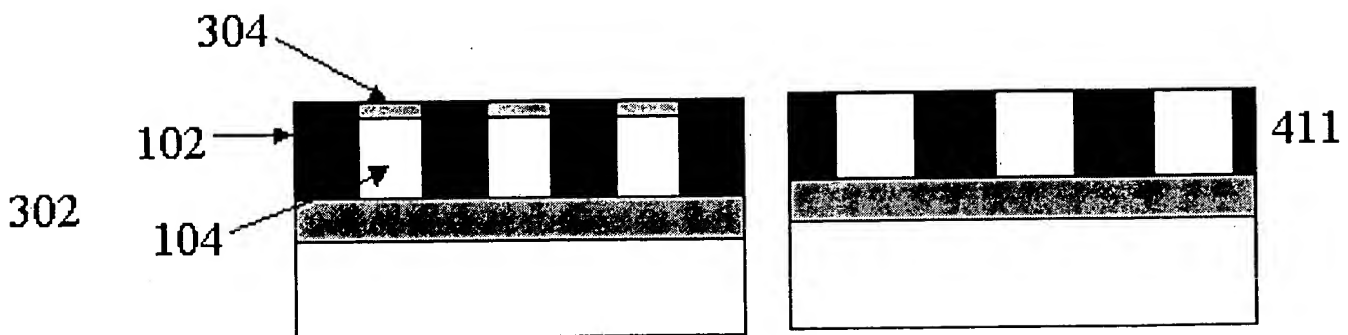
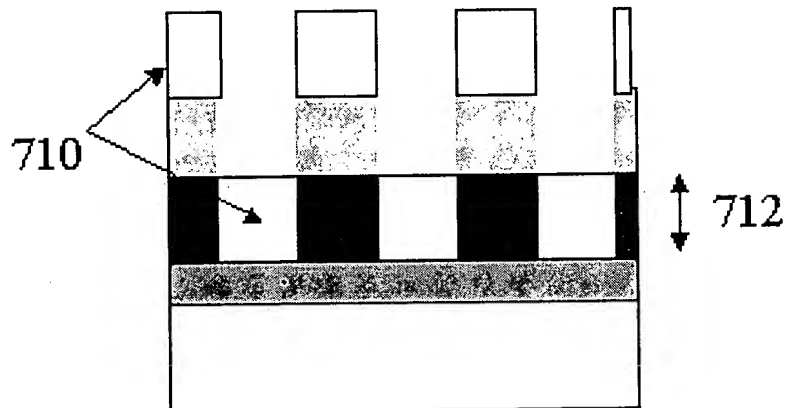
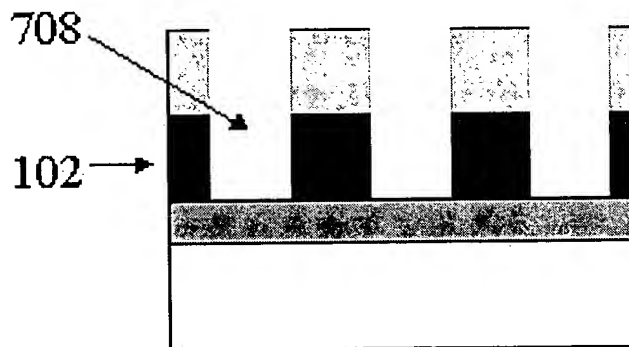
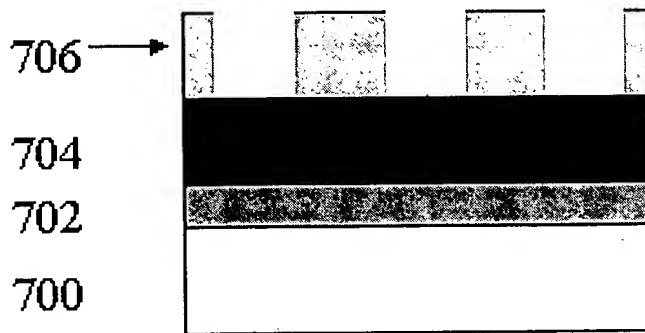


Figure 8

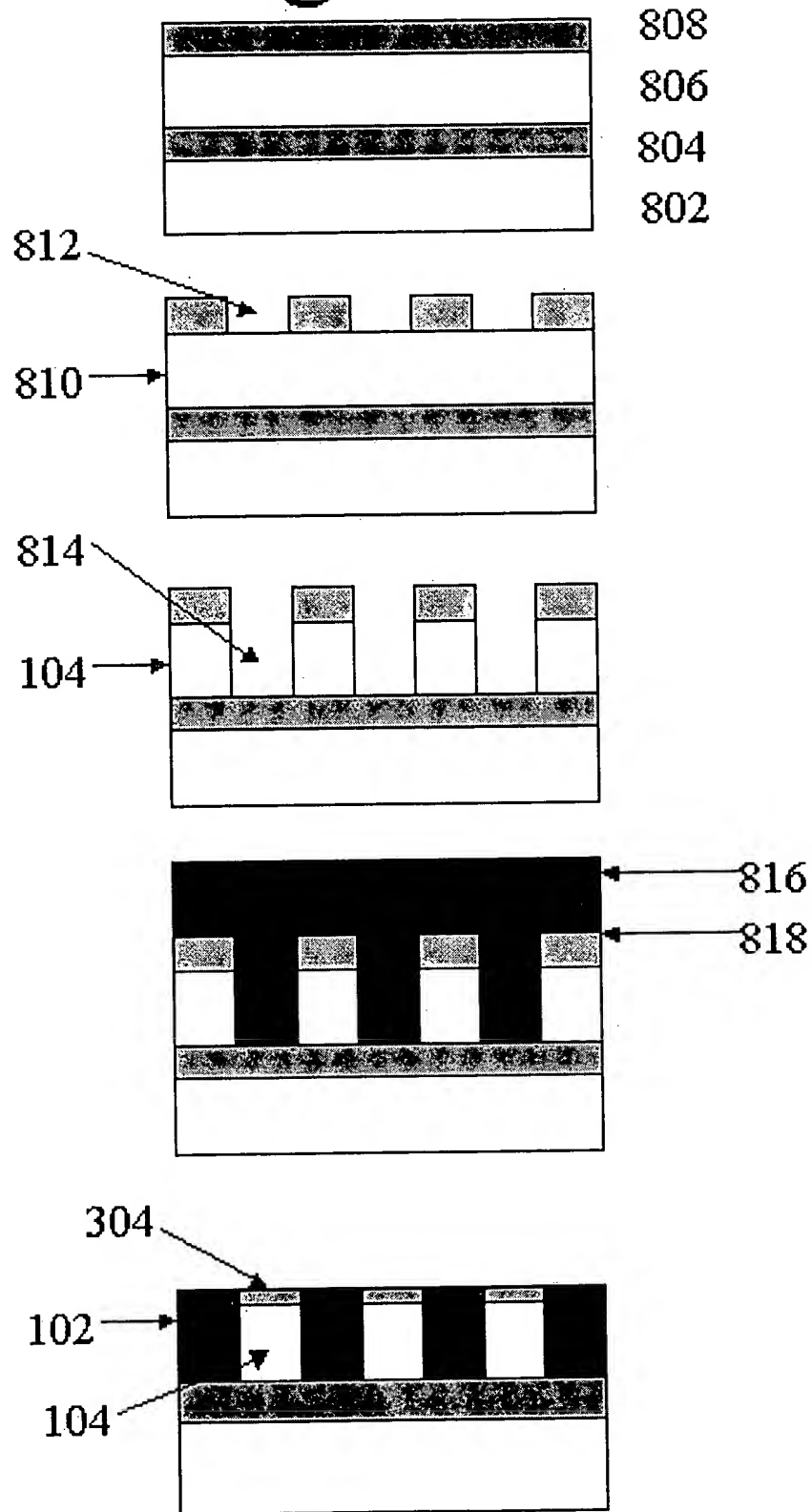


Figure 9

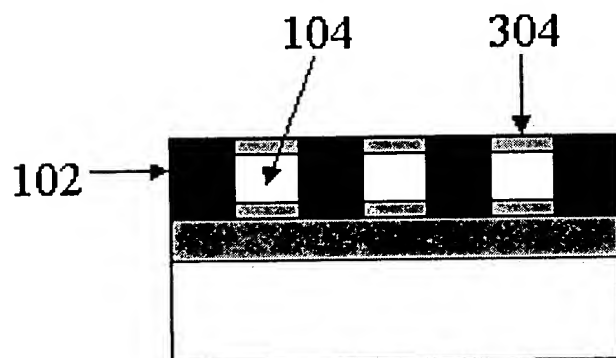
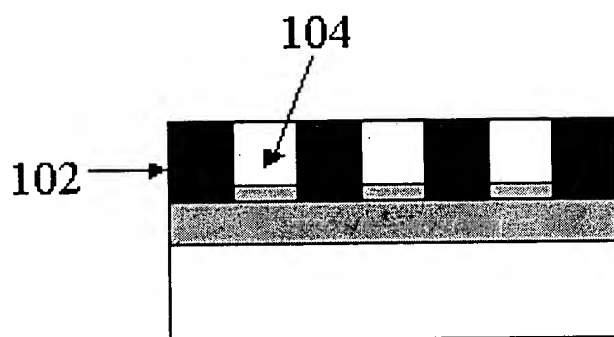
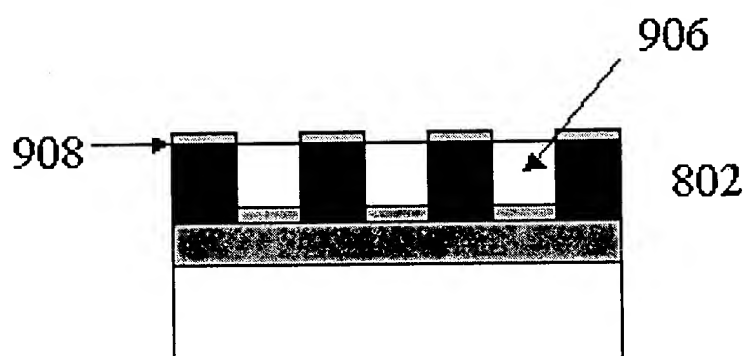
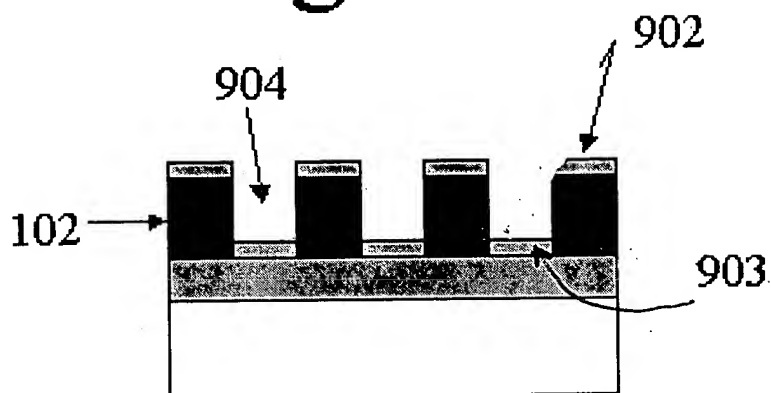


FIG. 9

411'

302''

Figure 10

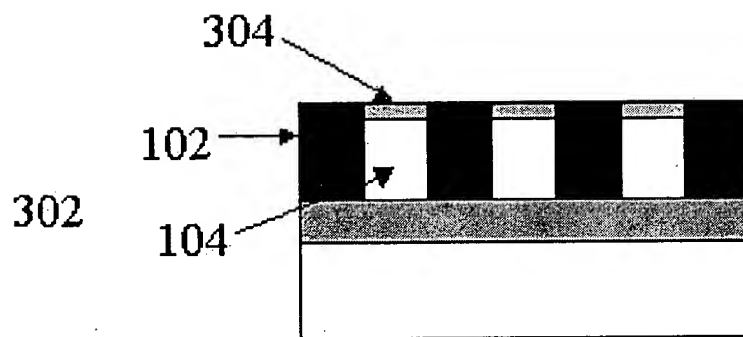
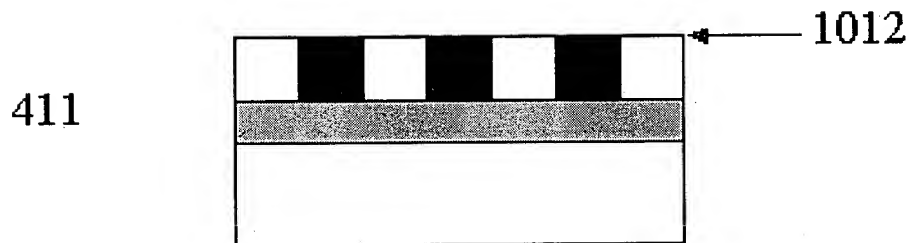
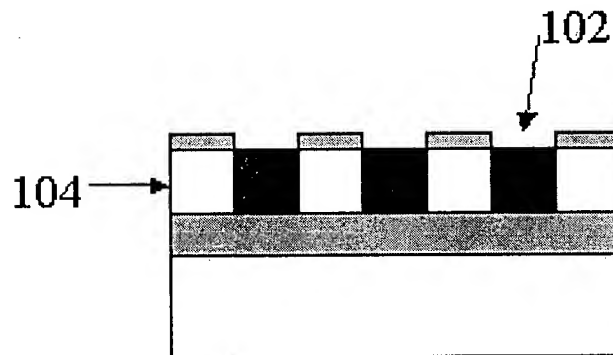
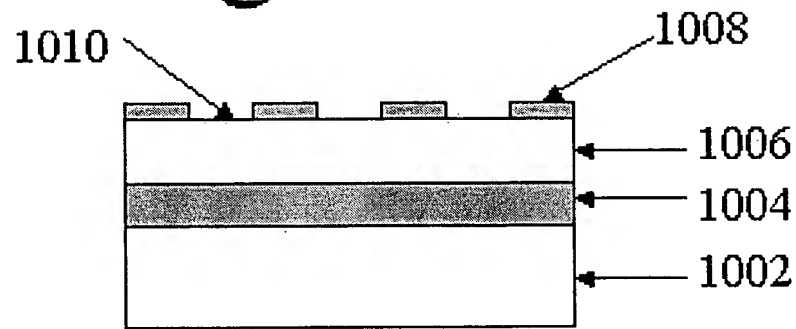


FIG. 10

Figure 11

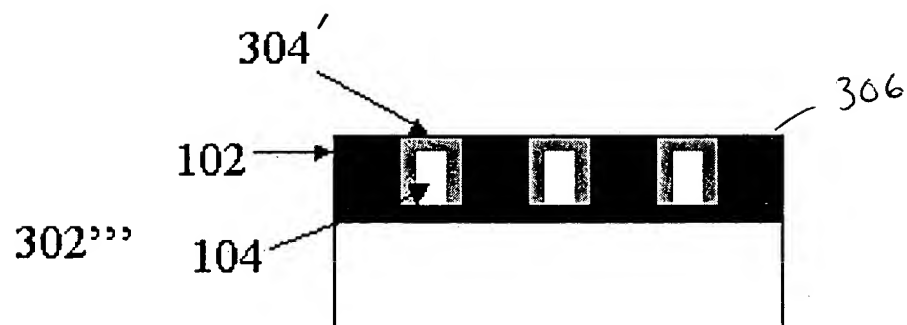
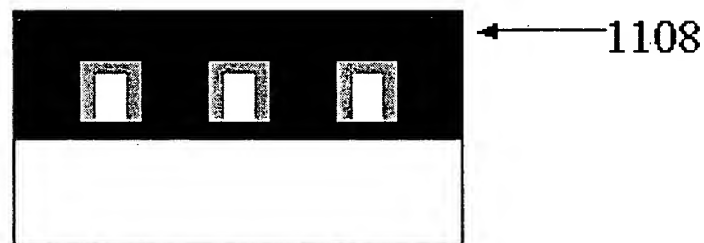
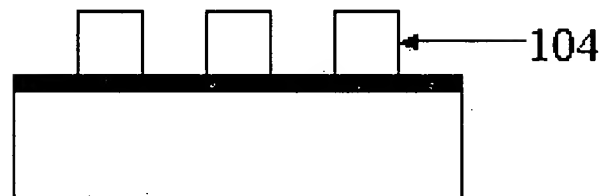


FIG. 11

Figure 12

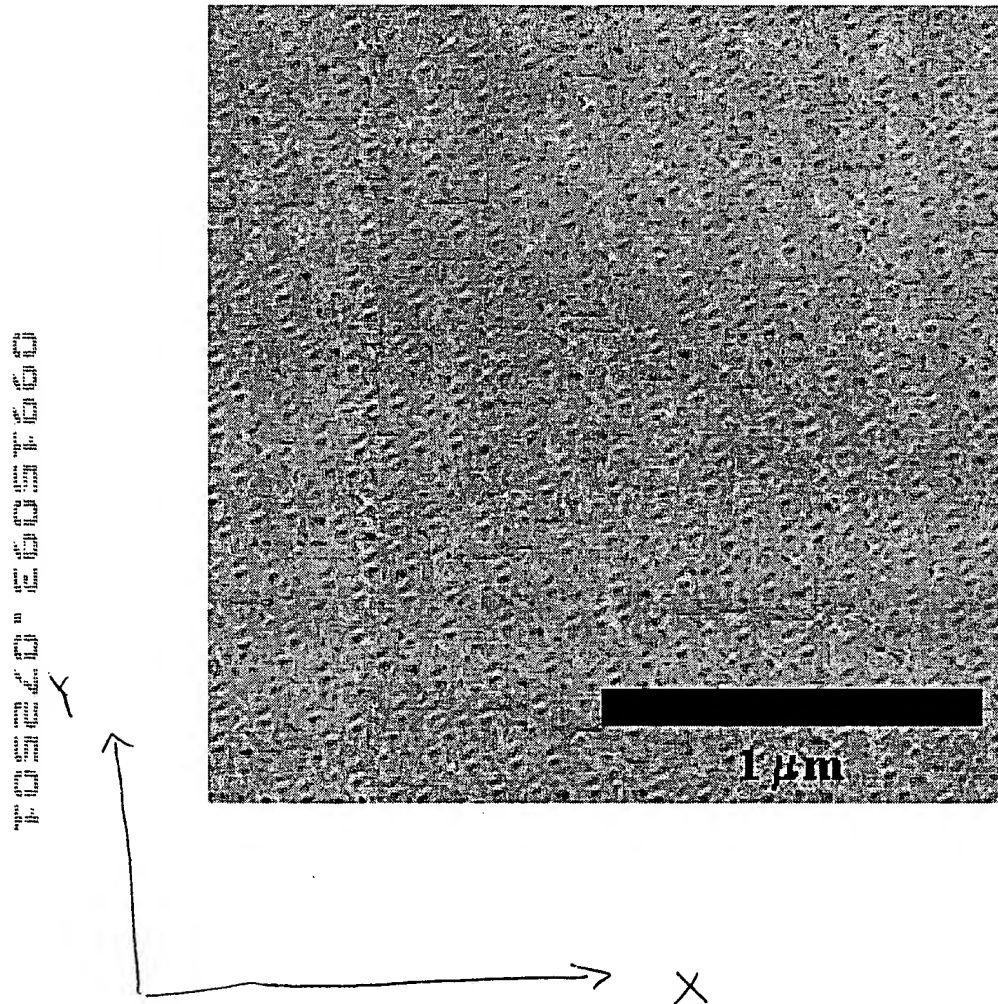


Figure 13

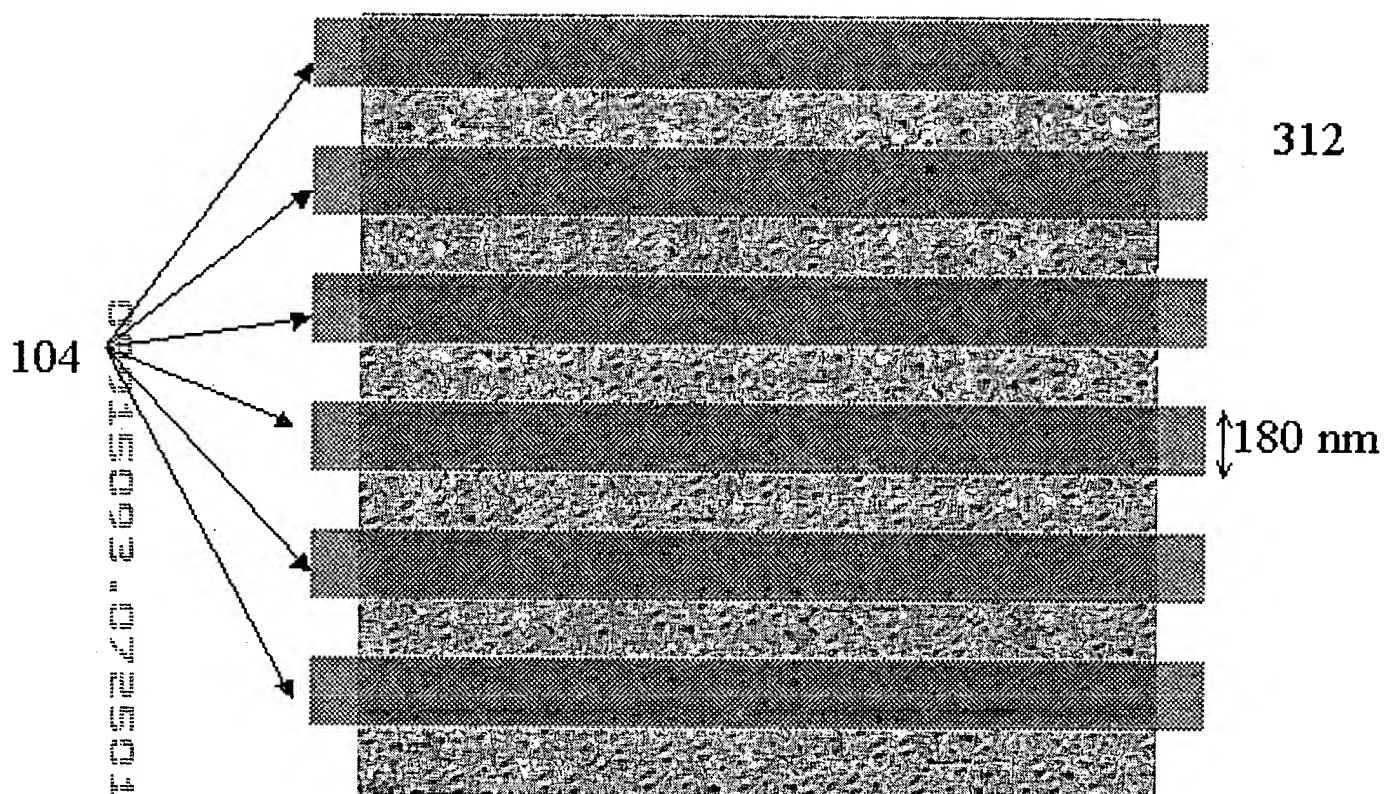


Figure 14

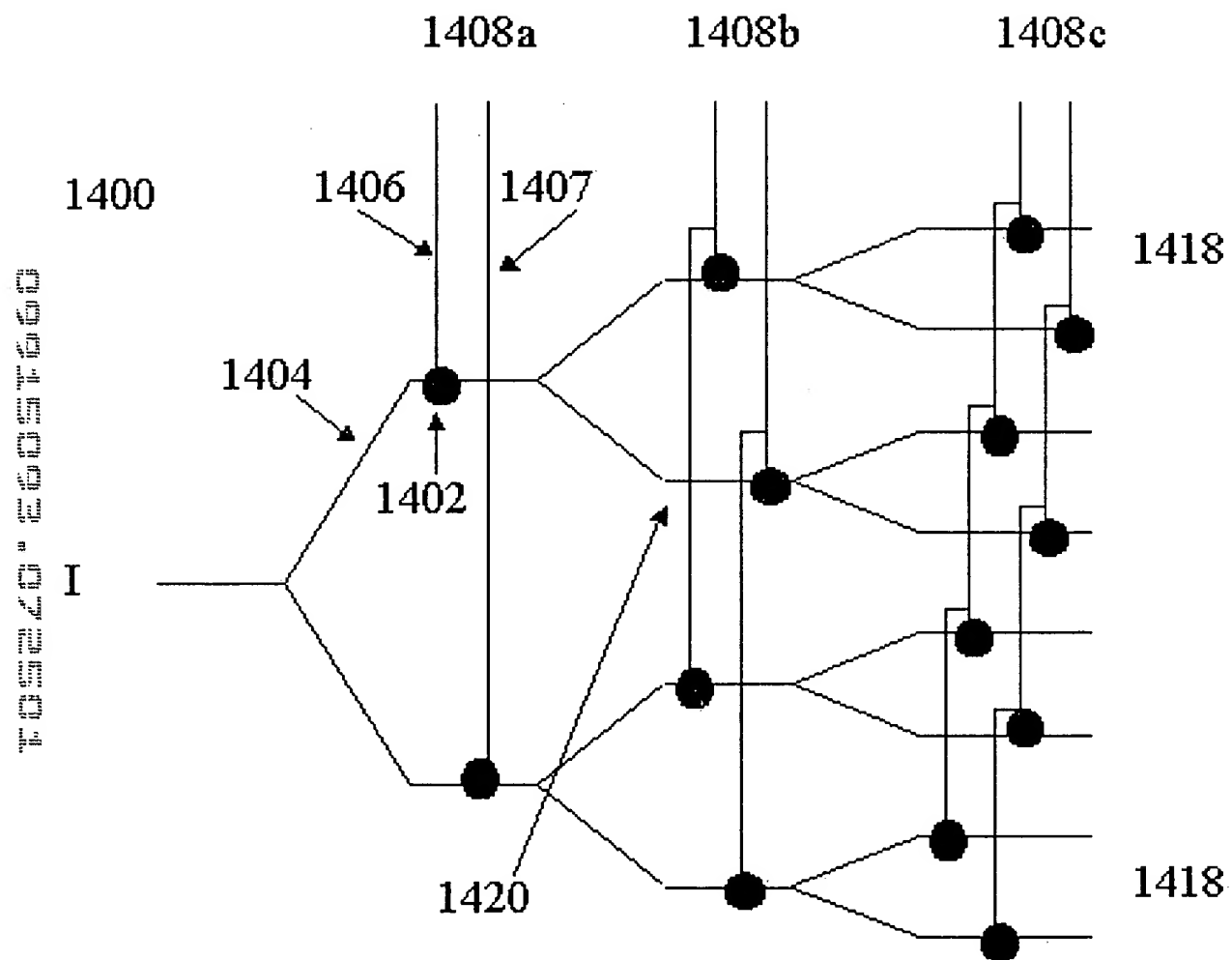


Figure 15

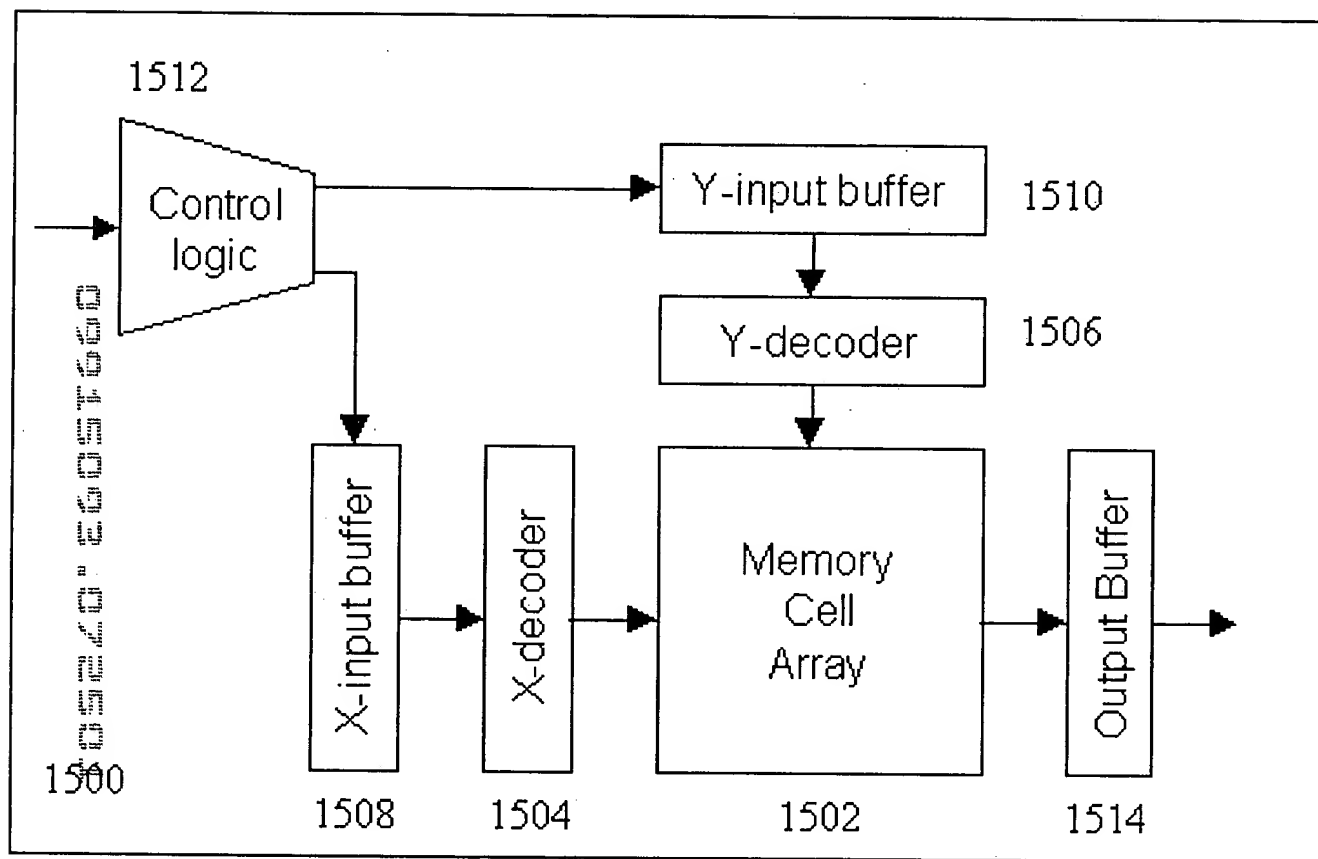


Figure 16

1600

